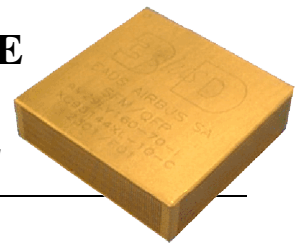




3D PLUS - SYSTEM IN PACKAGE

HOW TO BYPASS OBSOLESCENCE



General Description:

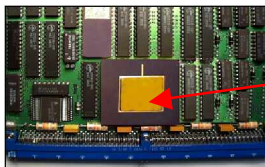
3D Plus patented technology allows our customers to replace an obsolete component by a pin-to-pin compatible 3D Plus module.

This technology fits with a wide range of electronic devices such as ASICs, digital and analog hybrid, memories...

In order to ensure that the new module will identically match the original application, 3D plus covers a full scope of fields to explore.

1. Architecture and Technology study

Gathering of all information and documents describing and characterizing the original component such as datasheet, specifications, timing analysis...

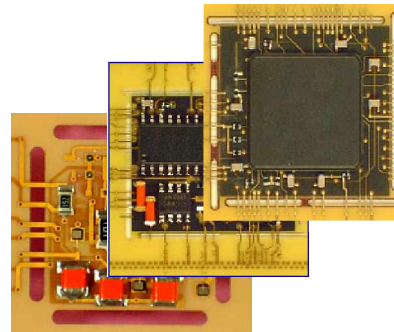


Obsolete component

2. Module Design and prototyping phase

3D Plus circuits design and prototyping including test development and implementation.

- Schematic analysis
- Power analysis
- Mechanical analysis
- Stacking study
- Circuit breakdown & Flex schematic design
- Flex layout
- Module mechanical drawing
- Design file
- Test development
- Test board design and manufacturing

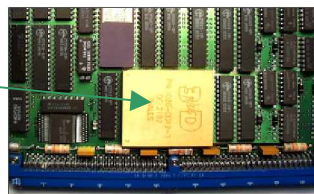


3. Manufacturing

3D Plus module fits exactly the obsolete component.

Same Functionality

Same Footprint



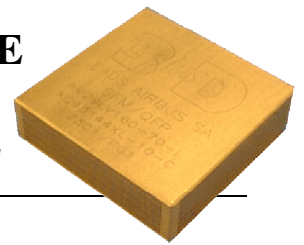
Same Pin-out

Same Power Voltage

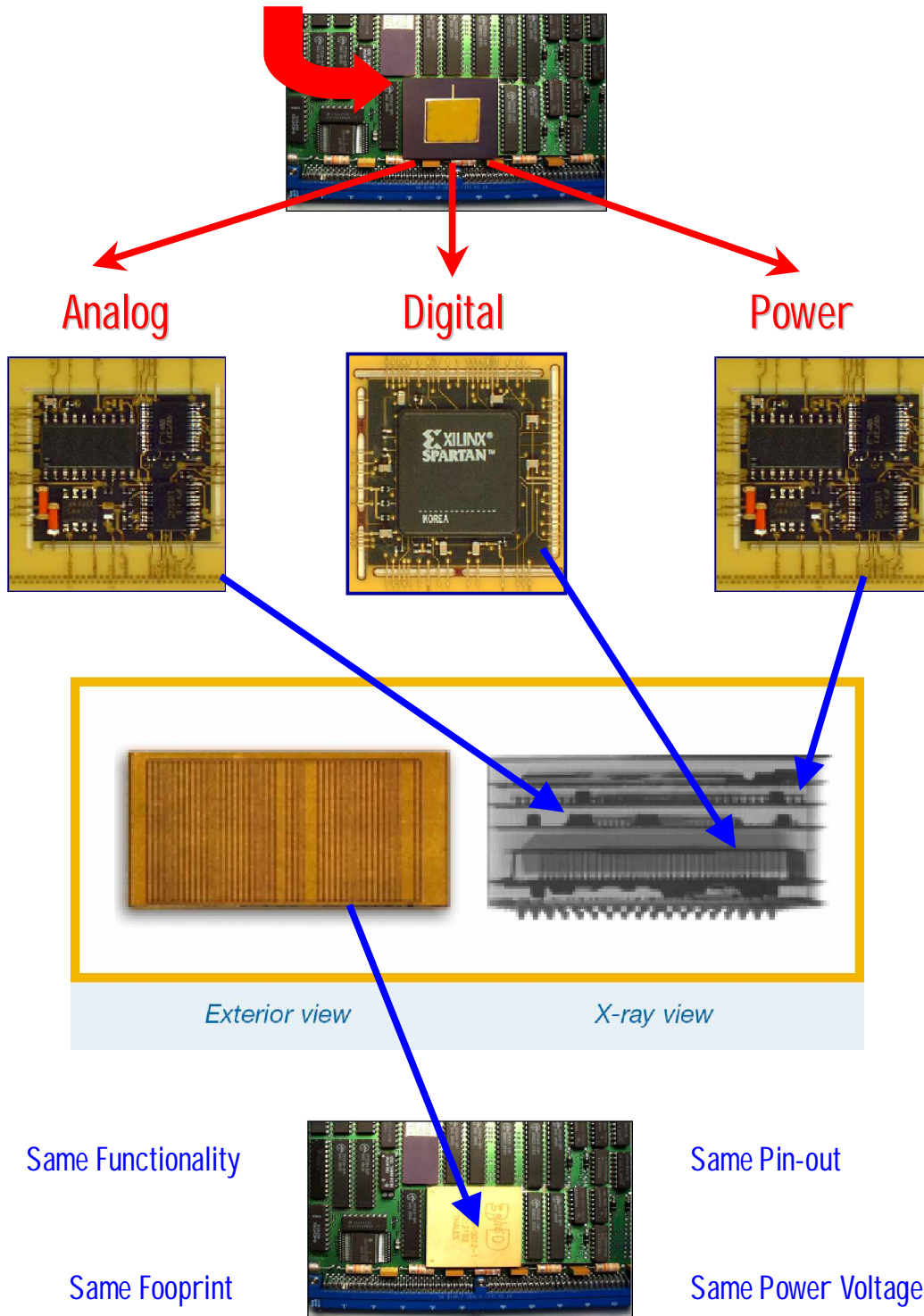


3D PLUS - SYSTEM IN PACKAGE

HOW TO BYPASS OBSOLESCENCE



Obsolete component



Main Sales Office:

FRANCE	3D PLUS 641, rue Hélène Boucher ZI. 78532 BUC Cedex	Tel : 33 (0)1 30 83 26 50	Fax : 33 (0)1 39 56 25 89	Web : www.3d-plus.com e-mail : sales@3d-plus.com
North America	3 D PLUS USA, Inc. 2570 Eldorado Park way, Suite 150 McKinney, TX 75070	Tel : (1) 214 733-8505	Tel : (1) 214733-8506	Web : www.3d-plus.com e-mail : jquinn@3d-plususa.com